

ABSTRACT

Sub A1
The present invention is intended to provide a resin and a resin composition that can be diluted with water and is excellent in providing a cured product (curing, adhesion, and water resistance); a resin composition that is suitable for a solder resist and an interlayer dielectric layer because the cured product is excellent in flexibility, soldering-heat resistance or the like and allows a development with an organic solvent or a dilute alkali solution; a photosensitive resin composition suitable for an etching resist or a cover lay; and a photosensitive film obtained thereby.

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A urethane oligomer (A) obtained by reacting a polyol compound(a) with a polybasic acid anhydride(b-1) having at least two acid anhydride groups per molecule, a polyisocyanate compound(c), and a hydroxy compound having ethylenically unsaturated groups; and

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A resin composition and a photosensitive film comprising (1) the above oligomer (A); (2) one or more resins selected from an unsaturated group-containing polycarboxylic acid (B), a reactive diluent(C-1) such as (meth)acrylates, an unreactive diluent(C-2) such as carbitol acetate and a thermoplastic polymer(D); and (3) a photopolymerization initiator.